

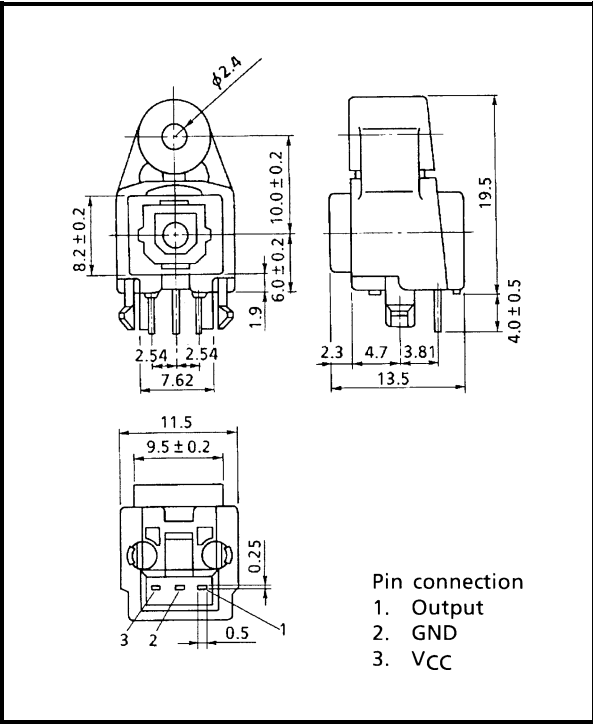
FIBER OPTIC RECEIVING MODULE

TORX141

Fiber Optic Receiving Module for Digital Audio Interface

Unit: mm

- Conform to JEITA standard CP-1201 (for digital audio interface including fiber optic inter-connections).
- A self-tapping hole for easy attachment to the panel of audio equipment.



Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Storage temperature	T _{stg}	-40 to 70	°C
Operating temperature	T _{opr}	-20 to 70	°C
Supply voltage	V _{CC}	-0.5 to 4.5	V
High level output current	I _{OH}	-2	mA
Low level output current	I _{OL}	2	mA
Soldering temperature	T _{sol}	260 (Note 1)	°C

Note 1: Soldering time ≤ 10 seconds. (More than 1 mm apart from package)

Recommended Operating Conditions

Characteristics	Symbol	Min	Typ.	Max	Unit
Supply voltage	V _{CC}	2.7	3.0	3.6	V

Electrical and Optical Characteristics (Ta = 25°C, VCC = 3 V)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Data rate		NRZ code (Note 2)	0.1	—	15	Mb/s
Transmission distance		Using APF (Note 3)	0.2	—	10	m
Pulse width distortion (Note 4)	Δt_w	Pulse Width 67 ns Pulse Cycle 134 ns CL = 10 pF Using TOTX141	−20	—	20	ns
Maximum receivable power (Note 5)	P _{MAX}	15 Mb/s, Using APF	−14.5	—	—	dBm
Minimum receivable power (Note 5)	P _{MIN}	15 Mb/s, Using APF	—	—	−27	dBm
Current consumption	I _{CC}		—	10	15	mA
High level output voltage	V _{OH}		2.1	2.5	—	V
Low level output voltage	V _{OL}		—	0.2	0.4	V

Note 2: High level output when optical flux is received. Low level output when optical flux is not received.
The duty factor must be kept 25 to 75%.

Note 3: All Plastic Fiber (970/1000 μm).

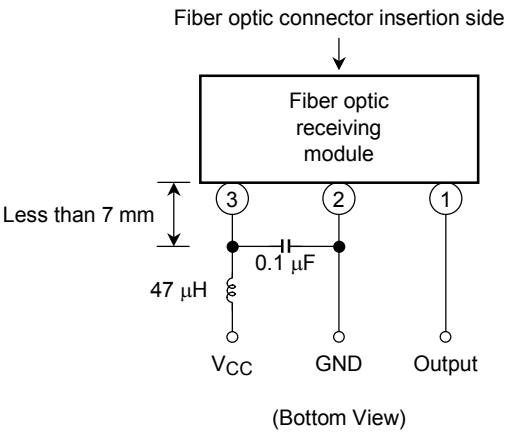
Note 4: Between input of TOTX141 and output of TORX141.

Note 5: BER ≤ 10^{−9}, peak value.

Mechanical Characteristics (Ta = 25°C)

Characteristics	Test Condition	Min	Typ.	Max	Unit
Mating force	Using TOCP172, Initial value	—	—	39.2	N
Unmating force	Using TOCP172, Initial value	5.9	—	39.2	N
Torque for self-tap	Using self-tapping screw (M3 × 8)	58.8	—	98	N·cm

Application Circuit



Applicable Optical Fiber with Fiber Optic Connectors

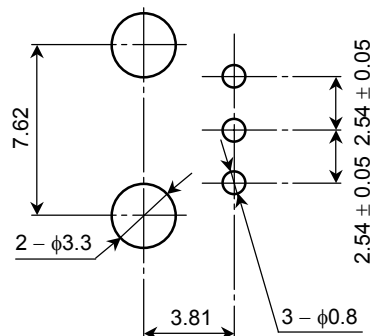
TOCP172-□□B

Board Layout Hole Pattern (for reference)

Unit: mm

Tolerance: ± 0.1 mm

Recommended PCB thickness: 1.6 mm



Precautions During Use

(1) Maximum rating

The maximum ratings are the limit values which must not be exceeded during operation of device. None of these rating value must not be exceeded. If the maximum rating value is exceeded, the characteristics of devices may never be restored properly. In some extreme cases, the device may be permanently damages.

(2) Soldering

Optical modules are comprised of internal semiconductor devices. However, in principle, optical modules are optical components. During soldering, ensure that flux does not contact with the emitting surface or the detecting surface. Also ensure that proper flux removal is conducted after soldering.

Some optical modules come with a protective cap. The protective cap is used to avoid malfunction when the optical module is not in use. Note that it is not dust or waterproof.

As mentioned before, optical modules are optical components. Thus, in principle, soldering where there may be flux residue and flux removal after soldering is not recommended. Toshiba recommend that soldering be performed without the optical module mounted on the board. Then, after the board has been cleaned, the optical module should be soldered on to the board manually.

If the optical module cannot be soldered manually, use non-halogen (chlorine-free) flux and make sure, without cleaning, there is no residue such as chlorine. This is one of the ways to eliminate the effects of flux. In such a cases, be sure to check the devices' reliability.

(3) Noise resistance

It is believed that the use of optical transfer devices improve noise resistance. In theory, optical fiber is not affected by noise at all. However, receiving modules which handle signals whose level is extremely small, are susceptible to noise.

TOSLINK improve noise resistance to use a conductive case. However, the current signal output by the optical receiving modules' photodiode is extremely small. Thus, in some environments, shielding the case may not achieve sufficient noise resistance.

For systems which incorporate TOSLINK, Toshiba recommend testing using the actual device to check its noise resistance.

Use a simple noise filter on TOSLINK fiber optic transceiving module's power line. If the ripple in the power supply used is significant, reinforce the filter.

The optical module is to be used in an area which is susceptible to radiated noise, increase the shielding by covering the optical module and the power line filter with a metallic cover.

(4) Vibration and shock

This module is plastic sealed and has its wire fixed by resin. This structure is relatively resistant to vibration and shock. In actual equipment, there are sometime cases in which vibration, shock, or stress is applied to soldered parts or connected parts, resulting in lines cut. A care must be taken in the design of equipment which will be subject to high levels of vibration.

(5) Support pins

The TORX141 has support pins in order to fix itself to the PCB temporary. Please make the hole for these pins in the PCB under the condition for described in board layout hole pattern.

- (6) Panel attachment
TORX141 has hole for panel attachment. Please be sure to attach it to panel with self-tapping screw.
- (7) Solvent
When using solvent for flux removal, do not use a high acid or high alkali solvent. Be careful not to pour solvent in to the optical connector ports. If solvent is inadvertently poured in to them, clean it off using cotton tips.
- (8) Protective cap
When the TORX141 is not in use, attach the protective cap.
- (9) Supply voltage
Use the supply voltage within the recommended operating condition ($V_{CC} = 2.7$ to 3.6 V). Make sure that supply voltage does not exceed the maximum rating value of 4.5 V, even for an instant.
- (10) Interface
The TORX141 has a TTL interface. It can be interfaced with any TTL-compatible C-MOS IC.
- (11) Output
If the receiver output is at low and is connected to the power supply, or if the output is high and is connected to GND, the internal IC may be destroyed.
- (12) Soldering condition
Solder at 260°C or less for no more than ten seconds.
- (13) Precautions when disposing of devices and packing materials.
When disposing devices and packing materials, follow the procedures stipulated by local regulations in order to protect the environment against contamination.
- (14) Precautions during use
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When developing equipment, please ensure that Toshiba products are used within the specified operating ranges set forth in the most recent product specifications. Also, please keep in mind the precautions and conditions set forth in the Toshiba Semiconductor Reliability Handbook.

RESTRICTIONS ON PRODUCT USE

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